



# ***AOS Semiconductor Product Reliability Report***

**AOZ7645LQI-13**, rev A

**Plastic Encapsulated Device**

**ALPHA & OMEGA Semiconductor, Inc**

**[www.aosmd.com](http://www.aosmd.com)**

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This AOS product reliability report summarizes the qualification results for AOZ7645LQI-13 in QFN6x6-17L package. Accelerated environmental tests are performed on a specific sample size and samples are electrically tested before and after each time point. Review of final electrical test results confirm that AOZ7645LQI-13 passes the AOS quality and reliability requirements. The released products will be categorized by its process family and routinely monitored for continuous improvement of product quality.

## I. Reliability Stress Test Summary and Results

Test Item	Test Condition	Time Point	Total Sample Size	Number of Failures	Reference Standard
HTOL	T <sub>J</sub> = 125°C, V <sub>IN</sub> = V <sub>ccmax</sub>	168 / 500 / 1000 hours	231 pcs	0	JESD22-A108
Preconditioning (Note A)	T <sub>A</sub> = 30°C, RH = 60% + 3 cycle reflow @ 260°C (MSL 3)	192hours	924 pcs	0	JESD22-A113
HAST	T <sub>A</sub> = 130°C, RH = 85%, P = 33.3psia, V <sub>IN</sub> = V <sub>ccmax</sub>	96 hours	231 pcs	0	JESD22-A110
Autoclave	T <sub>A</sub> = 121°C, RH = 100%, P = 29.7psia	96 hours	231 pcs	0	JESD22-A102
Temperature Cycle	T <sub>A</sub> = -65°C to 150°C, air to air	250 / 500 / 1000 cycles	231 pcs	0	JESD22-A104
HTSL	T <sub>A</sub> = 150°C	1000 hours	231 pcs	0	JESD22-A103

**Note:** The reliability data presents total of available generic data up to the published date.

Note A: MSL (Moisture Sensitivity Level) 3 based on J-STD-020

## II. Reliability Evaluation

**FIT rate (per billion): 50.97**

**MTTF = 2240 years**

The presentation of FIT rate for the individual product reliability is restricted by the actual burn-in sample size. Failure Rate Determination is based on JEDEC Standard JESD 85. FIT means one failure per billion hours.

**Failure Rate** =  $\text{Chi}^2 \times 10^9 / [2 (N) (H) (Af)] = 50.97$

**MTTF** =  $10^9 / \text{FIT} = 2240$  years

**Chi<sup>2</sup>** = Chi Squared Distribution, determined by the number of failures and confidence interval

**N** = Total Number of units from burn-in tests

**H** = Duration of burn-in testing

**Af** = Acceleration Factor from Test to Use Conditions (E<sub>a</sub> = 0.7eV and T<sub>use</sub> = 55°C)

Acceleration Factor **[Af]** =  $\text{Exp} [E_a / k (1/T_{J u} - 1/T_{J s})]$

**Acceleration Factor ratio list:**

	55 deg C	70 deg C	85 deg C	100 deg C	115 deg C	125 deg C
<b>Af</b>	<b>77</b>	<b>26</b>	<b>9.8</b>	<b>3.9</b>	<b>1.7</b>	<b>1</b>

T<sub>J s</sub> = Stressed junction temperature in degree (Kelvin), K = C + 273.16

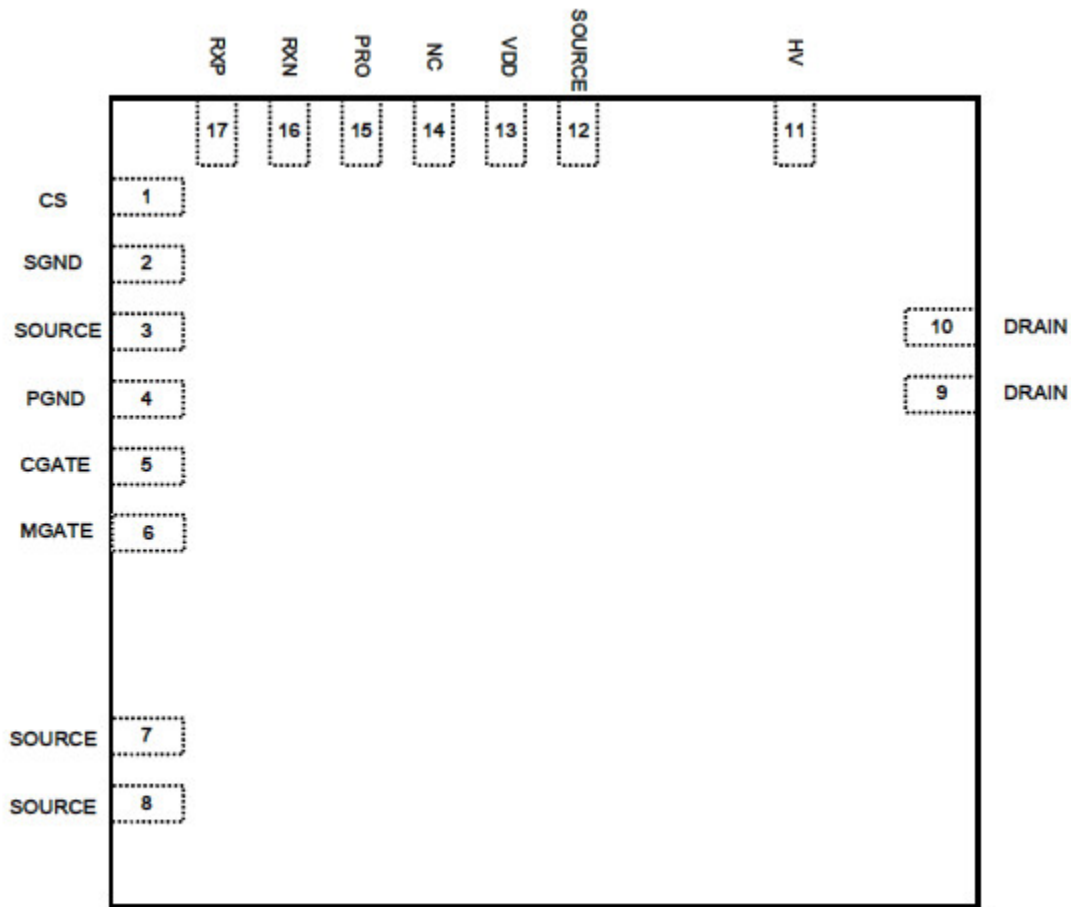
T<sub>J u</sub> = The use junction temperature in degree (Kelvin), K = C + 273.16

**k** = Boltzmann's constant, 8.617164 X 10<sup>-5</sup>eV / K

### III. ESD and Latch Up Test Results

Test	Test Conditions	Total Sample Size	Number of Failures	Reference Standard
Electrostatic Discharge Human Body Model	T <sub>A</sub> = 25°C, +/-4kV	3	0	JESD-A114
Electrostatic Discharge Charged Device Model	T <sub>A</sub> = 25°C, +/-1kV	3	0	JESD-C101
Latch Up	T <sub>A</sub> = 25°C, +/-100mA, 1.5x OV	6	0	JESD78
Latch Up	T <sub>A</sub> = 85°C, +/-100mA, 1.5x OV	6	0	JESD78

(1) ATE results are used to determine PASS/FAIL. Parametric shift <10%.



17-Pin 6mm x 6mm QFN  
(Top View)